

Application:

Intel LGA775 Wolfdale / Yorkfield (45nm) CPU
E8000/E7000/E6000/E5000/Q9000S/Q8000S
sequence

Thermal & Mechanical Spec.:

Thermal performance for 65W CPU
HSK Assembly Weight: 205 g (ref.)
Clipping Force: 20 Kgf (ref.)

Picture:



Component Specification:

1. Heat Sink

Type: Extruded HSK
Material: Aluminum A6063 or Equivalent.
Dimension: 90*90*19.05 mm

2. Thermal interface material

Material: Dow Corning TC-1996 or Equivalent.

3. Fan

(90x90x25 mm with Thermistor & PWM Control)

Rated Voltage: 12 V

Life Time:

Superflo bearing 50000 hrs

Connector:

a. Lead wire: UL 1430 AWG#26

pin 1: black wire-----(-)

pin 2: yellow wire-----(+)

pin 3: green wire----- (F00)

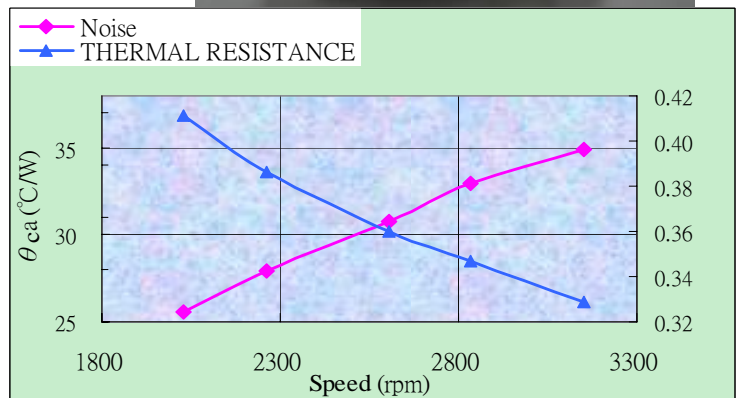
pin 4: blue wire----- (PWM)

b. Housing: Molex 47054-1000 or equivalent

c. Terminal: Molex 2759T 08-50-0113 or equivalent

* All readings are typical values at rated voltage.

* Specifications are subject to change without notice



Application:

Intel LGA775 Conroe-L Celeron CPU 400 series

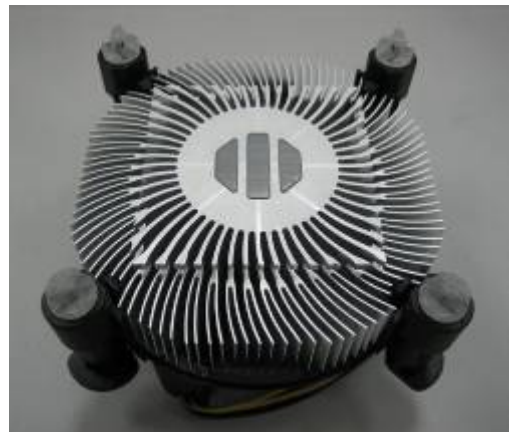
Thermal & Mechanical Spec.:

Thermal performance for 35W CPU
HSK Assembly Weight: 205 g (ref.)
Clipping Force: 20 Kgf (ref.)

Component Specification:

- Heat Sink
Type: Extruded HSK
Material: Aluminum A6063 or Equivalent.
Dimension: 90*90*19.05 mm
- Thermal interface material
Material: Dow Corning TC-1996 or Equivalent.
- Fan *(90x90x25 mm with single speed)*
Rated Voltage: 12 V
Life Time:
Superflo bearing 50000 hrs
Connector:
 - Lead wire: UL 1430 AWG#26
pin 1: black wire-----(-)
pin 2: yellow wire-----(+)
pin 3: green wire----- (F00)
 - Housing: Molex 2695-03 22-01-3037 or equivalent
 - Terminal: Molex 2759T 08-50-0113 or equivalent

Picture:



* All readings are typical values at rated voltage.
* Specifications are subject to change without notice

Application:

Intel LGA775 Yorkfield (45nm) CPU
Q9000/Q8000 sequence (Low Profile)

Picture:



Thermal & Mechanical Spec.:

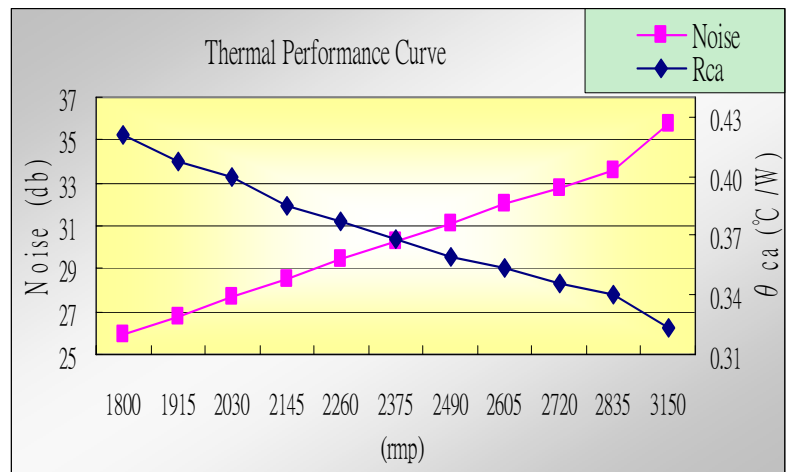
Thermal performance for 95W CPU
HSK Assembly Weight: 290 g (ref.)
Clipping Force: 20 Kgf (ref.)

Component Specification:

- Heat Sink
Type: Thermal Shrink with Cu Core
Material: Aluminum A6063 & Copper C1100 or Equivalent.
Dimension: 90*90*19.05 mm
- Thermal interface material
Material: Dow Corning TC-1996 or Equivalent.
- Fan *(90x90x25 mm with Thermistor & PWM Control)*
Rated Voltage: 12 V
Life Time:
Superflo bearing 50000 hrs
Connector:



- Lead wire: UL 1430 AWG#26
pin 1: black wire-----(-)
pin 2: yellow wire-----(+)
pin 3: green wire----- (F00)
pin 4: blue wire----- (PWM)
- Housing: Molex 47054-1000 or equivalent
- Terminal: Molex 2759T 08-50-0113 or equivalent



- * All readings are typical values at rated voltage.
- * Specifications are subject to change without notice